

**WHAT IS CLAIMED IS:**

1. A heat-resistant insulating film, comprising:  
a pattern profile corresponding to a structure with  
5 geometries including a convex or concave portion, the pattern  
profile being formed by three-dimensional forming for fitting  
onto the structure.
2. The heat-resistant insulating film according to claim 1,  
10 wherein a material of the film is a polyimide.
3. The heat-resistant insulating film according to claim 1,  
wherein the pattern profile includes an uneven profile having  
a ratio of a depth to an opening width less than or equal to  
15 two.
4. The heat-resistant insulating film according to claim 1,  
wherein the structure is a circuit board mounted with electronic  
components on the board.  
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5. The heat-resistant insulating film according to claim 1,  
wherein the three-dimensional forming is vacuum/compressed air  
forming.
- 25 6. The heat-resistant insulating film according to claim 1,  
wherein the three-dimensional forming is pressure forming using  
a die.

7. A method for insulating a structure to be insulated, comprising:

forming a heat-resistant insulating film into a pattern  
5 profile corresponding to a surface to be insulated of the structure with geometries including a convex or concave portion by three-dimensional forming; and

covering the surface to be insulated with the heat-resistant insulating film.

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8. The method according to claim 7, wherein a material of the film is a polyimide.

9. The method according to claim 7, wherein the pattern  
15 profile includes an uneven profile having a ratio of a depth to an opening width less than or equal to two.

10. The method according to claim 7, wherein the structure  
is a circuit board mounted with electronic components on the  
20 board.

11. The method according to claim 7, wherein the three-dimensional forming is vacuum/compressed air forming.

25 12. The method according to claim 7, wherein the three-dimensional forming is pressure forming using a die.